

Some Fabrication and Measurement Issues for High Gradient Test Accelerator Structures

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1. Work Updates

- TD24R05 Structures j
 - Motivation
 - Fabrication Status
- Structure Damage Studies

2. How to Produce High Quality Surfaces

- Chemical Cleaning
- Diffusion Bonding Process


1. Work Updates

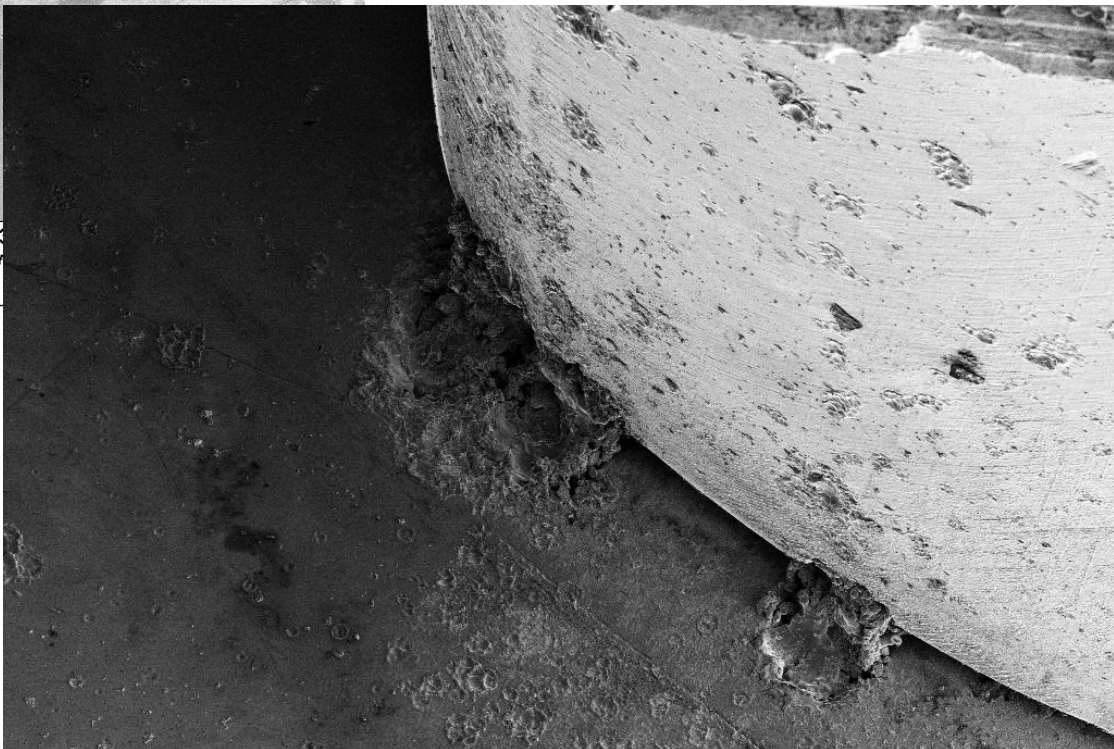
- TD24R05 Structures
 - Motivation
 - Fabrication Status one completed, 3 nearly completed.
- Structure Damage Studies


CERN Pictures for TD18 Structure after High Power Test

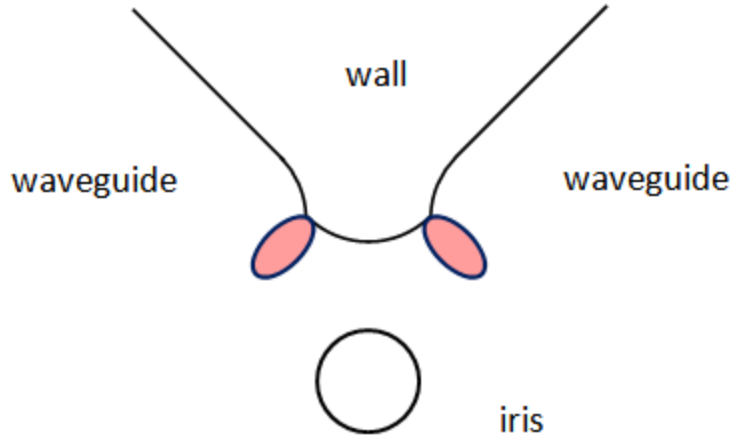
Part C
Down-stream side - Cell Wall S-W!
Tilt 30°



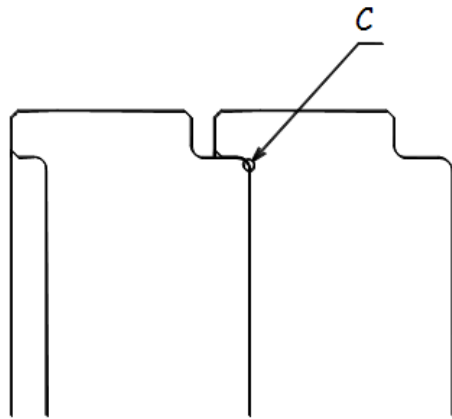
100 μm
 EHT = 5.00 kV TD18 KEK-SLAC Part C Tilt 30°
 WD = 15.4 mm Down-Stream -- Cell Wall S-W!
 Signal A = SE2 Stage at R = 135.0 °



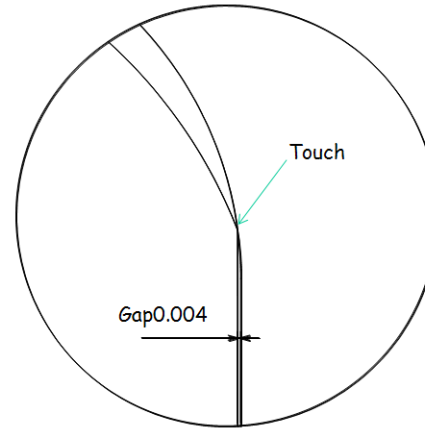
20 μm
 EHT = 5.00 kV TD18 KEK-SLAC Part C Tilt 30° Mag = 200 X
 WD = 15.4 mm Down-Stream -- Cell Wall S-W Markus Aicheler
 Signal A = SE2 Stage at R = 135.0 ° Date :30 Sep 2010



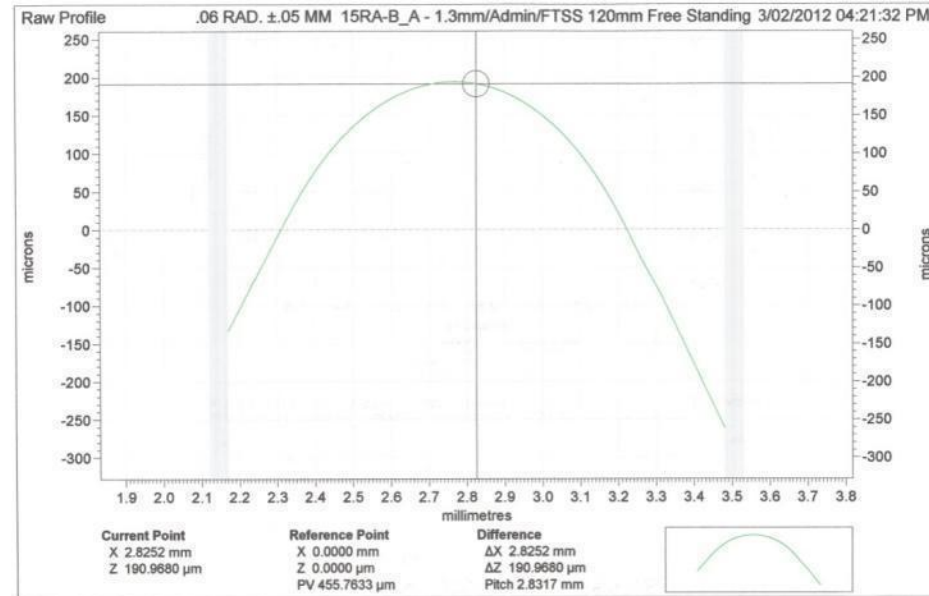
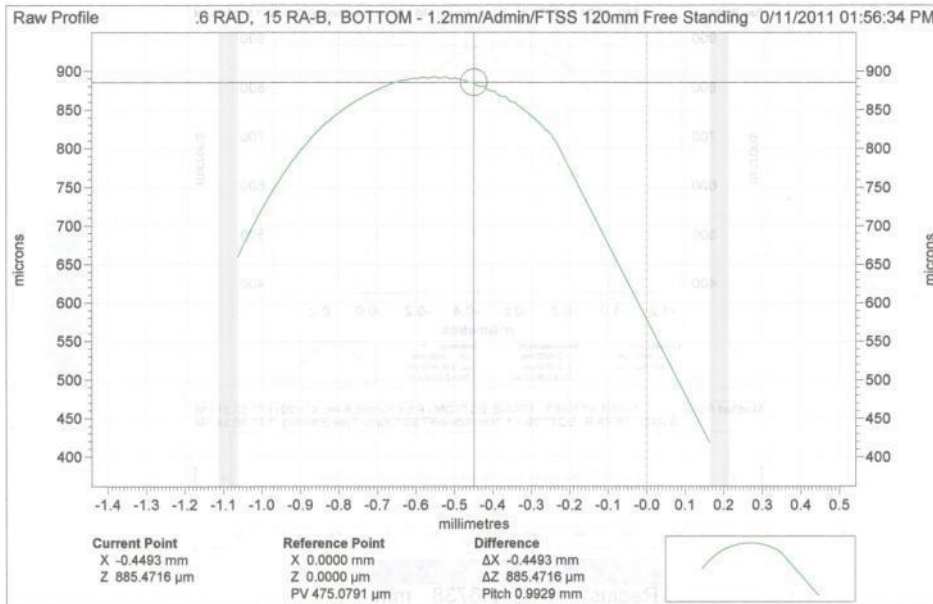
Delay due to Fabrication Problem and Correction



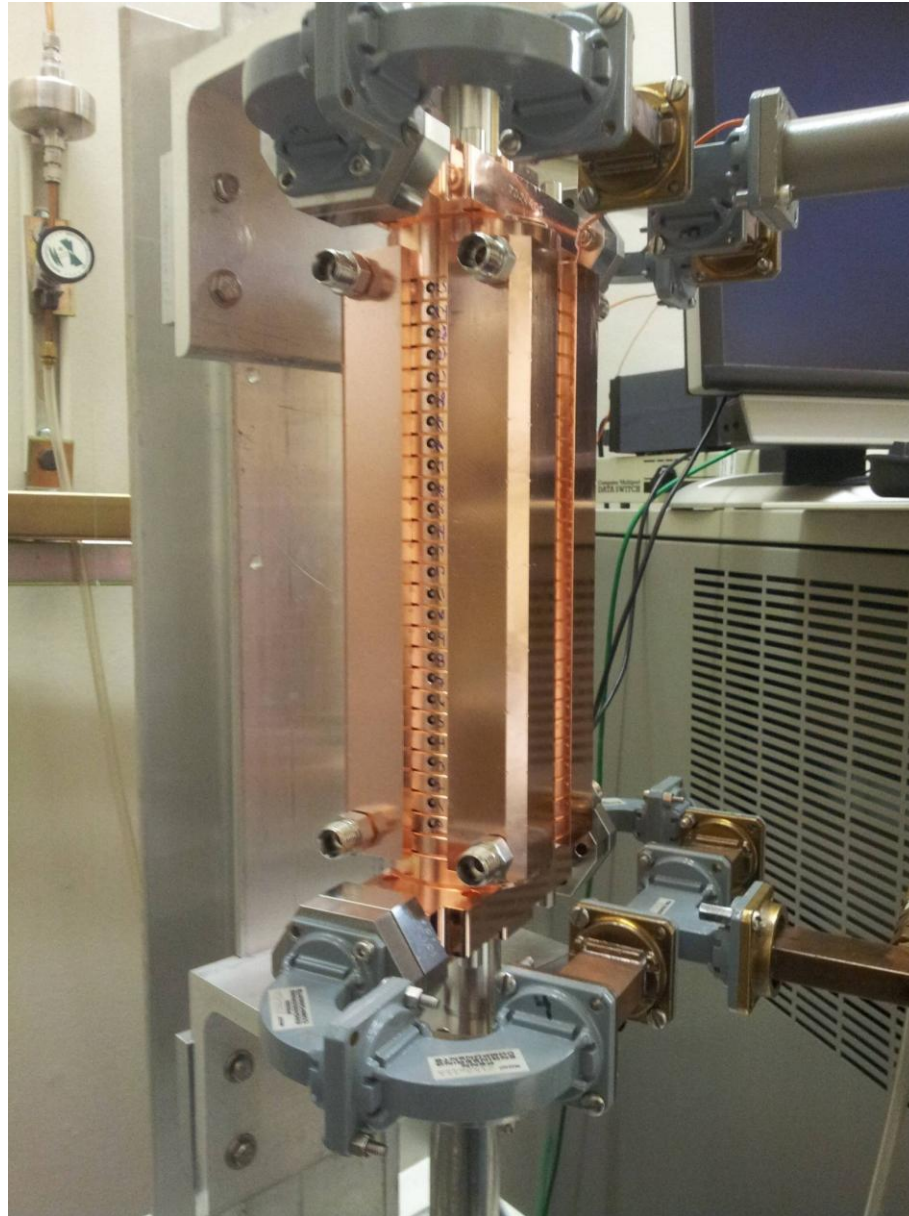
Taylor Hobson



Taylor Hobson

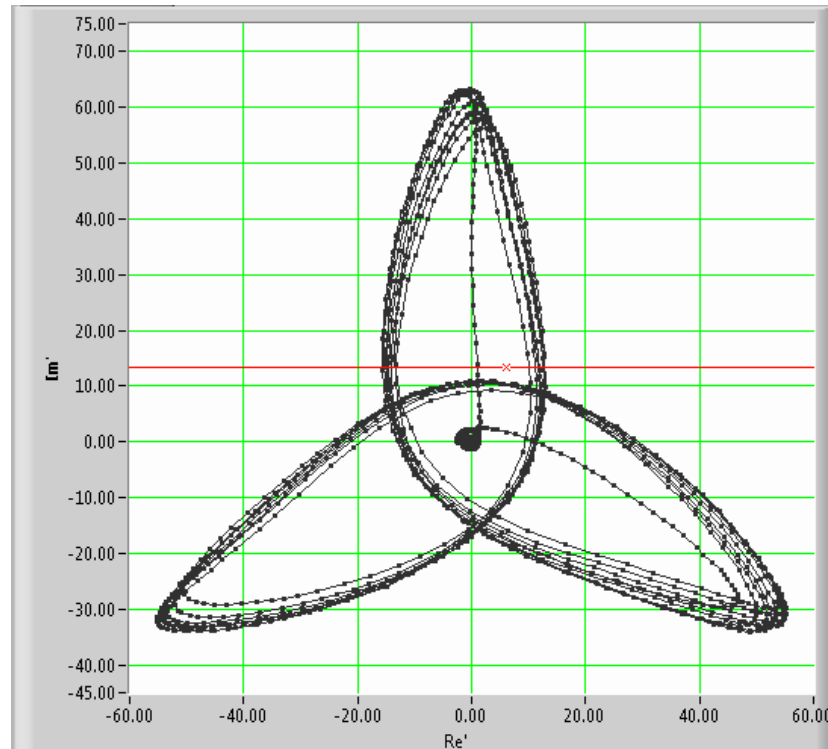


TD24R05 with KEK Flanges under Measurement

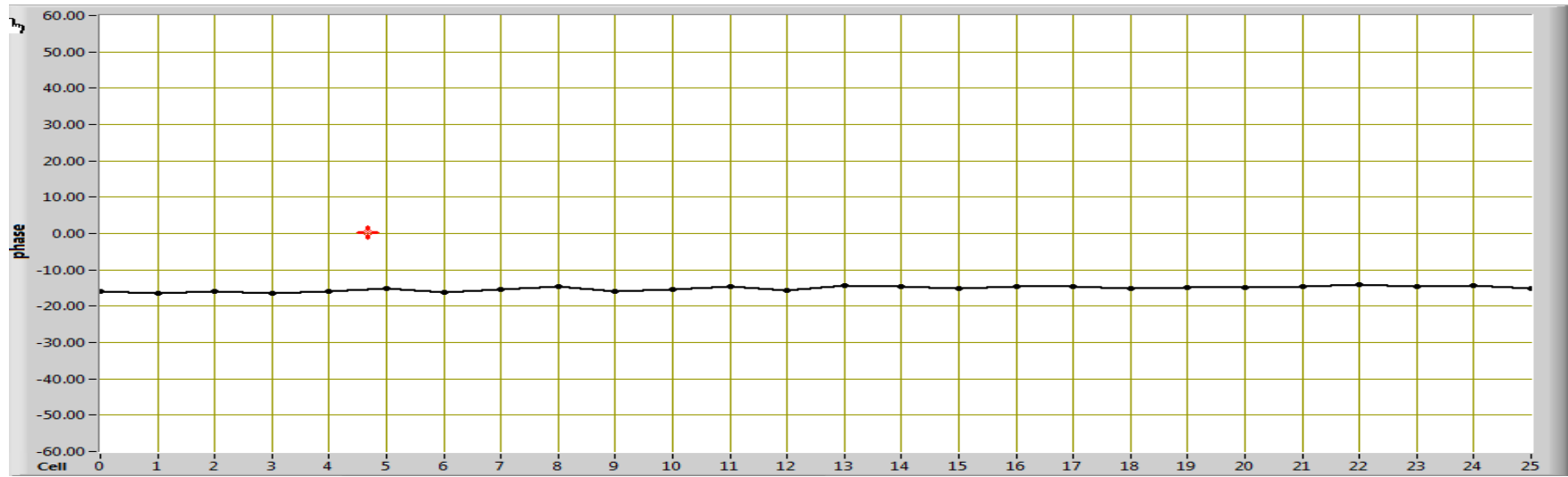
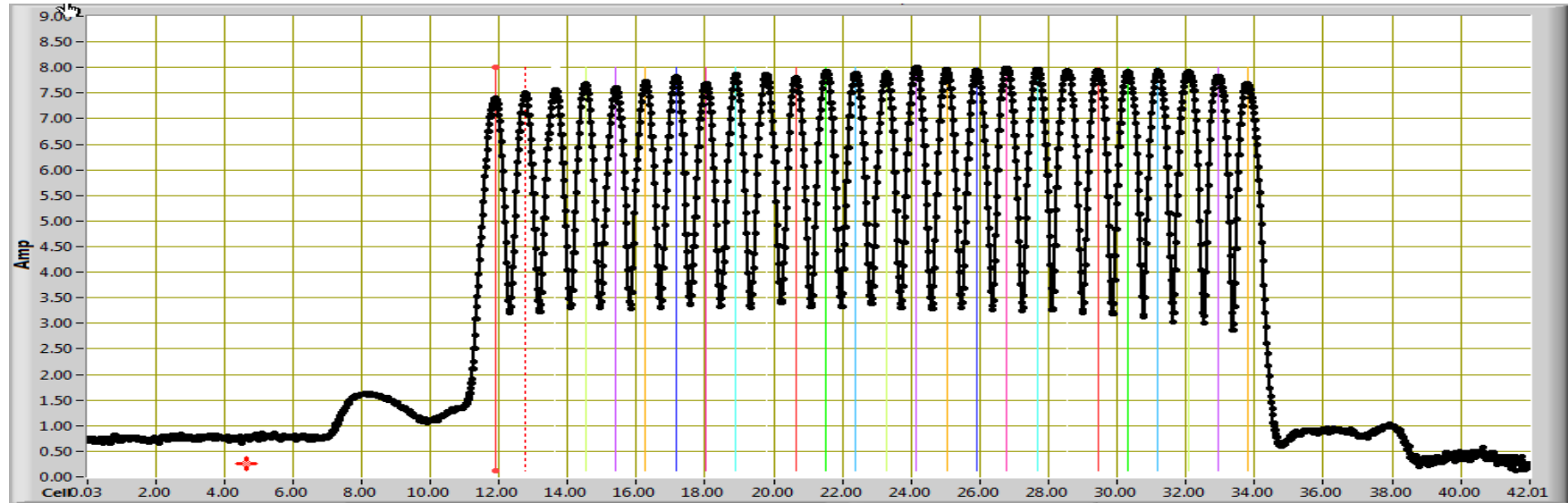


T24R05 Structure –KEK Flanges

- Operation Condition: 11424.0 MHz at 30°C, Vacuum
(Tuning at 11420.99, 22.2°C, dry Nitrogen with String)
- S11: 0.013
- S22: 0.042
- S12: 0.64
- Filling time: 58 ns



TD24R05 with KEK Flanges



Structure damage always is a critical issue for the life time and stabilization of the high gradient accelerating structures.

Structure Type	High Power Hours	Frequency Change	Output End Damage
T18-SLAC 100MV/m	1400	Very Small	Yes
T18-KEK 100MV/m	400	+ 1 MHz	Yes
TD18-SLAC 100 MV/m	700	+ 1 MHz	Yes
T24-SLAC 100 MV/m	600	-0.3 MHz	Yes
T24-KEK 100 MV/m	1600	+ 1 MHz	Yes
NCC/GLC Prototypes 65 MV/m	Few Hundreds	No	No

2. How to Produce High Quality Surfaces

- Chemical Cleaning
- Diffusion Bonding Process
- Following up Procedures

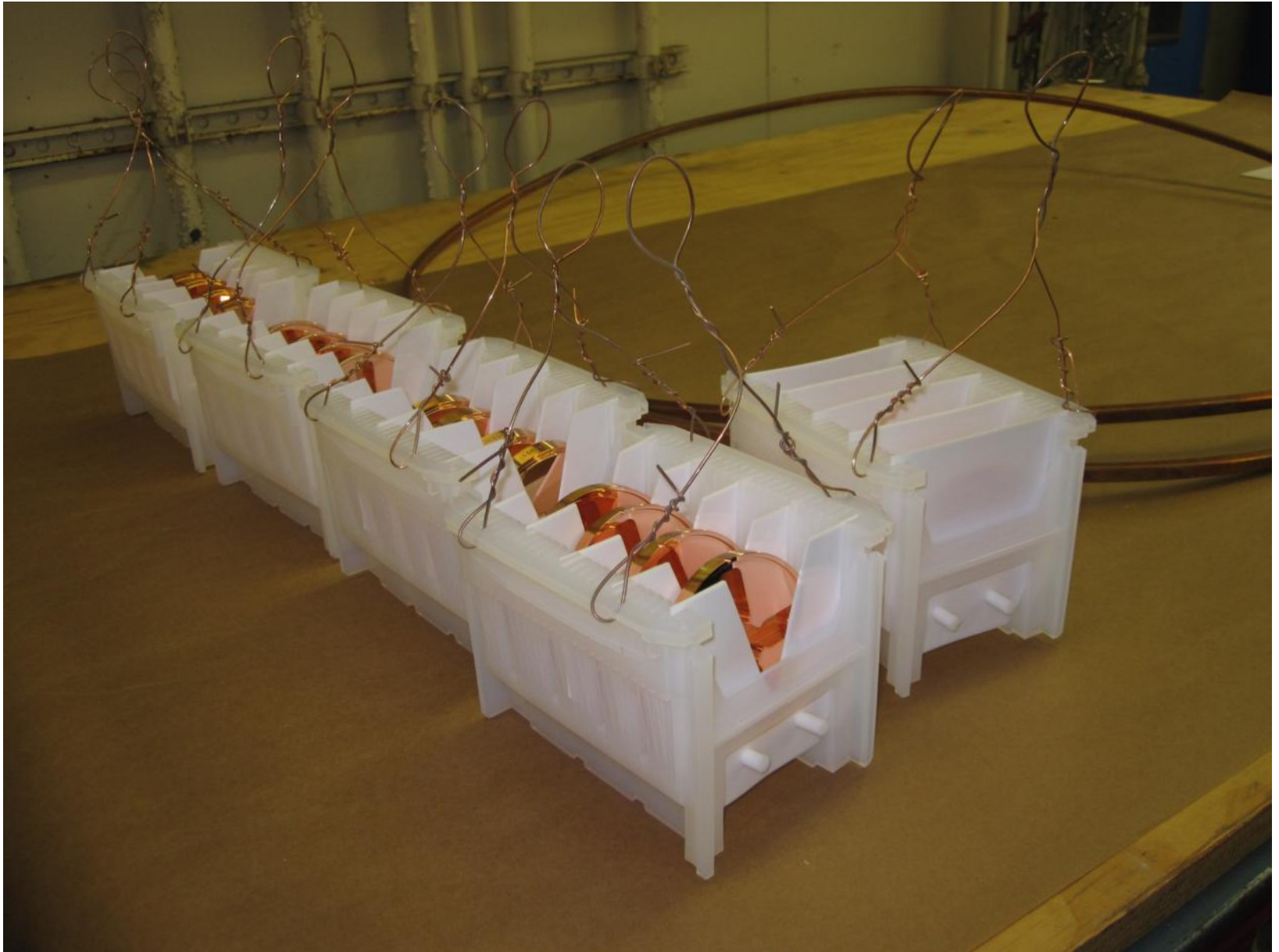
Label for Cleaning Procedure in Container

THIS SIDE UP

Clean **Diamond Turned** Copper Cells for T3145 Cell Set #2 per C01 except:
Etch time, step 6, to be **30 seconds** (1/10/11) per Juwen
Skip step 8 (no HCl/H₂SO₄)
Omit step 11, (no oxyban)
Ultrasonic in DI Water for 1 minute.
Ultrasonic in new, clean alcohol for 1 minute.
Final Rinse to be done in new, clean alcohol.
Hold in clean alcohol in stainless steel containers until just prior to Brazing.
Copper Coupler Halves will be dried by Tube Shop personnel in a Klystron clean room using filtered N₂.

cells 15RAB, 15MAB, 201B, 202B

Accelerator Cups Ready to be Cleaned



Vapor degrease in percoloroethylene for 5 minutes



Alkaline soak clean in Enprep Q527 for 5 minutes at 180°F.



Cold tap water rinse for 2 minutes.



Immense in 50% hydrochloric acid at room temperature for 1 minutes.



Immense in 50% hydrochloric acid at room temperature for 1 minutes.



5. Cold tap water rinse for 1 minute.



Immense in the following solution for the time depending on the surface finish required:

Phosphoric Acid, 75%	21 gallons
Nitric Acid, 42° Baume	7 gallons
Acetic Acid, Glacial	2 gallons
Hydrochloric Acid	12.6 fluid ounces
Temperature	Room



Cold tap water rinse for minimum of 2 minutes until the film on part disappears.



Rinsing the Tuning Holes



Ultrasonic in DI Water for 1 minute.



Ultrasonic in new, clean alcohol for 1 minute.



Hold in clean alcohol in stainless steel container



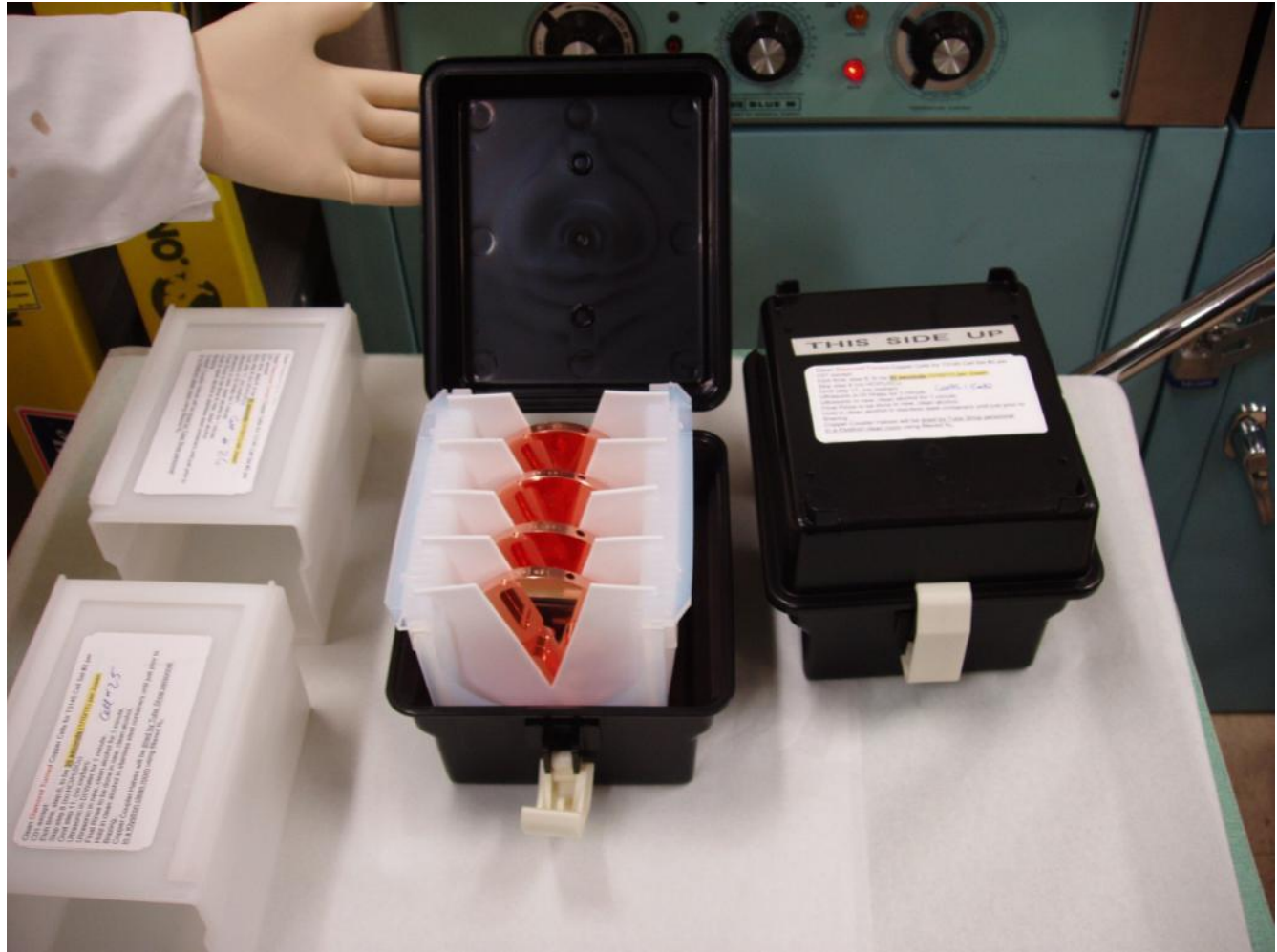
Ready to Ship for Diffusion Bonding



Blow Dry



Ready to Move to Furnace Area



Stacking in the Furnace



Ready for Diffusion Bonding



Proper Weight Added



Checking the Notchs Beteen Cups